

Occasional users: (hourly system)

- Daily access rate of \$45/day per user (min ½ day charge).
- Any work requiring technical help will be charged at an additional \$45/hr.
- Additional equipment use charges will apply as per the Equipment Rate schedule at bottom of page.

Frequent users: (flat rate system)

Frequent users are encouraged to use the flat rate system.

- The **flat rate** system provides researchers with access to the majority of the equipment in the facility without additional equipment charges and daily rate charges. (some exceptions include LPCVD furnaces, Semicore sputtering system)

-\$1545 per four month academic term or \$4120 per year per student. (Here “student” includes PDFs, research engineers, and others making active use of the facility)

This includes up to three hours per week of technical assistance and furnace runs up to a limit of 8 per term.

or

-\$3090 per term/\$8240 per year, per principal investigator, covering up to four students/researchers with the same limits on furnace runs and technical assistance as above.

Materials Costs

Access Fees include the cost of “basic” materials in the small quantities required for typical research projects. Basic materials include standard positive photoresist and developer (\$1811 is currently used), aqueous HCl, NH₄OH and HF for RCA cleans, isopropanol and acetone, chemicals for photomask making, oxygen and HCl gas for furnaces, and aluminum for metallization. The rationale for not accounting for the consumption of these basic materials by individual users is that the costs involved are usually small and that almost all users require these materials.

Aside from the “basic materials” listed above, all users are responsible for the cost of other materials they consume. This includes silicon substrates, photomasks, specialty gases (in particular silane), liquid nitrogen for substrate cooling in the Plasmatherm ECR etcher, and precious metals for deposition.

In the unlikely case that a user requires very large amounts of basic materials (for example, if a user is coating dozens of wafers with photoresist), additional basic materials charges may be levied.

Equipment Rates

- Atmospheric Furnace runs : \$75 for hydrogen or inert ambient anneals, \$100 for most other runs.
- LPCVD furnace runs : typically \$100 per run plus gas costs. (ie. Silane, Dichlorosilane, etc).
- Prefurnace clean (RCA): \$60 (2”wafers), \$75 (4”wafers) if required.
- SEM use \$15/hour (\$45/hour if assisted)
- Mask Aligner(MA6): \$35/hr (includes use of photoresist spinner and development bench)
- Wetbenches: \$15/hr
- Balzers Ebeam/Thermal Evaporator/Varian PVD: \$50/run (plus source material costs)
- Semicore inline sputtering system: \$90/run (plus source material costs)
- Plasmatherm ECR etcher: \$25/hr
- MRC RIE etcher: \$25/hr
- Profilometers/Ellipsometers: \$15/hr
- Optical Microscopes: \$15/hr